Title (en)

Wired circuit board and producing method thereof

Title (de)

Leiterplatte und Verfahren zu deren Herstellung

Title (fr)

Carte de circuit câblée et procédé de production correspondant

Publication

EP 2012566 A2 20090107 (EN)

Application

EP 08159609 A 20080703

Priority

JP 2007177510 A 20070705

Abstract (en)

A wired circuit board (1) includes a metal supporting board (2) having a depressed portion (5), a conductive portion (6) embedded in the depressed portion (5) and formed of a material having a higher conductivity than that of the metal supporting board (2), an insulating layer (7) formed on the metal supporting board (2) so as to cover the conductive portion (6), and a plurality of wires (4) formed on the insulating layer (7) in mutually spaced-apart relation so as to oppose to the conductive portion (6). A method for producing the same.

IPC 8 full level

H05K 1/05 (2006.01); **H05K 3/44** (2006.01)

CPC (source: EP US)

H05K 1/05 (2013.01 - EP US); **H05K 1/056** (2013.01 - EP US); **H05K 3/44** (2013.01 - EP US); H05K 2201/09745 (2013.01 - EP US); H05K 2201/10416 (2013.01 - EP US); H05K 2203/0323 (2013.01 - EP US); H05K 2203/0369 (2013.01 - EP US); H05K 2203/0723 (2013.01 - EP US); Y10T 29/49124 (2015.01 - EP US)

Citation (applicant)

- JP 2005011387 A 20050113 - HITACHI GLOBAL STORAGE TECH
- JP 2006245220 A 20060914 - NITTO DENKO CORP

Designated contracting state (EPC)

DE FR GB

Designated extension state (EPC)

AL BA MK RS

DOCDB simple family (publication)

EP 2012566 A2 20090107; **EP 2012566 A3 20091125**; **EP 2012566 B1 20110216**; CN 101340773 A 20090107; CN 101340773 B 20120229; DE 602008004949 D1 20110331; JP 2009016610 A 20090122; US 2009008137 A1 20090108; US 8354597 B2 20130115

DOCDB simple family (application)

EP 08159609 A 20080703; CN 200810130430 A 20080704; DE 602008004949 T 20080703; JP 2007177510 A 20070705; US 21651108 A 20080707